

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Number 6,875,634 B2
Issued 4/5/2005
Name of Patentee Il Kwon Shim et al.
Title of Invention HEAT SPREADER ANCHORING AND GROUNDING METHOD AND
THERMALLY ENHANCED PBGA PACKAGE USING THE SAME

ATTN: Certificate of Correction Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT

Please issue a Certificate of Correction for the following mistakes in the above-referenced patent.

☒ **FOR PTO MISTAKE (37 C.F.R. § 1.322(a))**

The exact page and line number where the errors are shown correctly in the application file are:

1. In the Preliminary Amendment dated 3/18/2004, page 2, item no. 2
2. In the specification, page 3, line 22
3. In the specification, page 8, line 2
4. In the specification, page 13, claim 11 (issued as claim 1), line 5
5. In the specification, page 13, claim 11 (issued as claim 1), line 7
6. In the specification, page 14, claim 12 (issued as claim 2)
7. In the specification, page 15, claim 19 (issued as claim 8), line 7
8. In the Preliminary Amendment dated 3/18/2004, page 9, claim 22 (issued as claim 11), line 19, step (d)

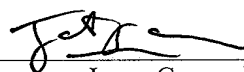
CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R.1.8a)

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☒ Submitted to the: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 via Electronic Filing System

Date: March 5, 2009

Signature _____



Joana Gunawan

The exact column and line number where the error occurs in the Patent are:

1. Column 2, line 50, delete "FIGS. 6b through 6c" and insert therefor --FIGS. 6b and 6c--
2. Column 2, line 62, delete "beat spreader" and insert therefor --heat spreader--
3. Column 6, line 5, delete "chemically a non-conductive material" and insert therefor --chemically treating the first surface of heat spreader 14 with a non-conductive material--
4. Column 8, claim 1, line 44, delete "semicoductor" and insert therefor --semiconductor--
5. Column 8, claim 1, line 48, delete "conductor" and insert therefor -- semiconductor --
6. Column 9, claim 2, line 18-21,
delete "said anchor posts comprising deposits of thermally and electrically conductive material, said thermally and electrically conductive material having been cured after deposition thereof."
and insert therefor --said anchor posts being created during said die attach process.--
7. Column 9, claim 8, line 47, delete "mateial." and insert therefor --material.--
8. Column 10, claim 11, line 13, delete "material said" and insert therefor --material, said--

COMMENTS

All mistakes are of a clerical nature, a typographical nature, or mistakes of minor character. None of the proposed corrections constitute new matter.

☒ Attached hereto is Form PTO/SB/44.

☒ Please send the Certificate to:

Name Mikio Ishimaru
Address Law Offices of Mikio Ishimaru
333 W. El Camino Real, Suite 330
Sunnyvale, CA 94087

☐ Charge Deposit Account 50-0374 the sum of \$0.00, as required by 37 CFR 1.20(a), and the fee for ____ additional copies of the Certificate of Correction. A duplicate of this request is attached.

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Date: March 5, 2009

UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

Page 1 of 1

PATENT NO. : 6,875,634 B2
APPLICATION NO. : 10/804,732
ISSUE DATE : April 5, 2005
INVENTOR(S) : Shim, et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 2

line 50, delete "FIGS. 6*b* through 6*c*" and insert therefor --FIGS. 6*b* and 6*c*--

line 62, delete "beat spreader" and insert therefor --heat spreader--

Column 6

line 5, delete "chemically a non-conductive material" and insert therefor
--chemically treating the first surface of heat spreader **14** with a non-conductive material--

Column 8

claim 1, line 44, delete "semicoductor" and insert therefor --semiconductor--

claim 1, line 48, delete "conductor" and insert therefor -- semiconductor --

Column 9

claim 2, line 18-21,

delete "said anchor posts comprising deposits of thermally and electrically conductive material, said thermally and electrically conductive material having been cured after deposition thereof."

and insert therefor --said anchor posts being created during said die attach process.--

claim 8, line 47, delete "mateial." and insert therefor --material.--

Column 10

claim 11, line 13, delete "material said" and insert therefor --material, said--

MAILING ADDRESS OF SENDER (Please do not use customer number below):

Mikio Ishimaru
Law Offices of Mikio Ishimaru
333 W. El Camino Real
Suite 330
Sunnyvale, CA 94087

This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. **SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.**

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